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PATENT AND TRADEMARK OFFICE	6550-000013/COA	10/730,398
INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)	APPLICANT	
	Biehler, et al.	
Sheet 1 of 3	FILING DATE	GROUP
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U.S. PATENT DOCUMENTS

Ref. Desig.	Examiner's Initials	Document Number	Date	Name	Class/ Subclass	(If appropriate) Filing Date
1.		3,481,795*	12/1969	Lane		
2.		4,248,905*	12/1981	Harvey		
3.		4,358,884*	11/1982	Harvey et al.		
4.		4,506,822*	3/1985	Hammersand et al.		
5.		5,066,544*	11/1991	Betrabet et al.		
6.		5,094,700*	3/1992	Sekhar		
7.		5,344,607*	9/1994	Gonya et al.		
8.		5,429,689*	7/1995	Shangguan et al.		
9.		5,527,628*	6/1996	Anderson et al.		

* Previously submitted in an IDS in parent application.

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

Ref. Desig.	Examiner's Initials	
1.		Anderson, et al., "Microstructural Modifications and Properties of Sn-Ag-Cu Solder Joints Induced By Alloying", Journal of Electronic Materials, vol. 31, no. 11, pp. 1166-1174 (2002)
2.		Attarwala, A.I. et al., "Confirmation of Creep and Fatigue Damage in Pb/Sn Solder Joints," J. Electron. Packag. 114:109-111 (1992)*
3.		Betrabet, H.S. et al., "Processing Dispersion-Strengthened Sn-Pb Solders To Achieve Microstructural Refinement And Stability," Script Metall. 25:2323-2328 (1991)*
4.		Betrabet, H.S. et al., "Towards Increased Fatigue Resistance In Sn-Pb Solders By Dispersion Strengthening," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1276-1277 (1992)*
5.		Clough, R.B. et al., "Preparation And Properties Of Reflowed Paste And Bulk Composite Solder," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1256-1265 (1992)*
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7.		Gibson, A.W. et al., "Issues Regarding Microstructural Coarsening Due To Aging Of Eutectic Tin-Silver Solder," Des. Reliab. Solders Solder Interconnect., Proc. Symp. (1997), 97-103*
8.		Ho, C.T. et al., "Carbon fiber reinforced tin-lead alloy as a low thermal expansion solder preform," *J. Mater. Res.* 5(6):1266-1270 (1990)*
9.		Jin, S., "Solder Materials Issues In High-Density Interconnection And Packaging," *Final Program ASM-TMS Materials Week '96*, ASM International and The Minerals, Metals & Materials Society, Cincinnati, Ohio, pp. 116 (1996)*
10.		Kuo, C.G. et al., "Fatigue Deformation Of In-Situ Composite Solders," 1st Int'l. Conf. Microstructures and Mechanical Properties of Aging Materials, ed. P.K. Liaw, R. Viswanathm, K.L. Murty, E.P. Simonen and D.R. Frear, The Minerals Metals & Materials Society, TMS, Warrendale, PA, pp. 417-423 (1993)*
11.		Kuo, C.G. et al., "Tensile And Creep Properties Of In-Situ Composite Solders," 1st Int'l. Conf. Microstructures and Mechanical Properties of Aging Materials, ed. P.K. Liaw, R. Viswanathm, K.L. Murty, E.P. Simonen and D.R. Frear, The Minerals Metals & Materials Society, TMS, Warrendale, PA, pp. 409-415 (1993)*
12.		Lau, J.H. et al., "Solder Joint Fatigue In Surface Mount Technology: State of the Art," Solid State Tech. pp. 91-104 (1985)*
13.		Lewis, R. (Ed.), Hawley's Condensed Chemical Dictionary, Thirteenth Ed., p. 483*
14.		Marshall, J.L. et al., "Composite Solders," IEEE Trans. Comp. Hybrids Manuf. Tech. 14(4):698-702 (1991)*
15.		Marshall, J.L. et al., "Microcharacterization Of Composite Solders," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1278-1283 (1992)*
16.		McCormack, M. et al., "Enhanced Solder Alloy Performance by Magnetic Dispersions," IEEE Trans. Comp. Hybrids Manuf. Tech.-Part A 17(3):452-457 (1994)*
17.		McCormack, M. et al., "The Design and Properties of New, Pb-Free Solder Alloys," Proc. IEEE/CPMT Int'l Electronics Manufacturing Technology Symp. pp. 7-14 (1994)*
18.		Miller, et al., "A Viable Tin-Lead Solder Substitute: Sn-Ag-Cu", Journal of Electronic Materials, vol. 23, no. 7, pp. 595-601 (1994).
19.		Moon, et al., "Experimental and Thermodynamic Assessment of Sn-Ag-Cu Solder Alloys", Journal of Electronic Materials, vol. 29, no.10, pp. 1122-1136 (2000)

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20.		Pinizzotto, R.F. et al., "Microstructural Development In Composite Solders Caused By Long Time, High Temperature Annealing," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1284-1298 (1992)*
21.		Sastry, S.M.L., et al., "Microstructures And Mechanical Properties Of In-Situ Composite Solders," Proc. Conf. NEPCON, West Anaheim, CA, pp. 1266-1275 (1992)*
22.		Shangguan, D. et al., "Evaluation of Lead-Free Eutectic Sn-Ag Solder For Automotive Electronics Packaging Applications," Proc. IEEE/CPMT Int'l Electronics Manufacturing Technology Symp., pp. 25-37 (1994)*
23.		Shine, M.C. et al., "Fatigue of Solder Joints in Surface Mount Devices," ASTM STP 942:588-610 (1988)*
24.		Smithells Metals Reference Book, 7th ed., Butterworth Heinemann, Oxford, 1992, p. 11-242, "Adapted Sn-Ag-Cu Phase Diagram"*
25.		Tien, J.K. et al., "Creep-Fatigue Interactions in Solders," IEEE Trans. Comp. Hybrids Manuf. Tech. 12(4):502-505 (1989)*
26.		Wasynczuk, J.A. et al., "Shear Creep Of Cu_6Sn_5/Sn-Pb Eutectic Composites," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1245-1255 (1992)*
27.		Weinbel, R.C. et al., "Creep-fatigue interaction in eutectic lead-tin solder alloy," J. Mater. Sci. 22:3901-3906 (1987)*

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